Complementary General Purpose Transistor

The NST3946DXV6T1 device is a spin-off of our popular SOT-23/SOT-323 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-563 six-leaded surface mount package. By putting two discrete devices in one package, this device is ideal for low-power surface mount applications where board space is at a premium.

- h_{FE}, 100–300
- Low $V_{CE(sat)}$, $\leq 0.4 \text{ V}$
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count

Table 1. MAXIMUM RATINGS

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Rating	Symbol	Value	Unit		
Collector – Emitter Voltage (NPN) (PNP)	V _{CEO}	40 -40	Vdc		
Collector – Base Voltage (NPN) (PNP)	V _{CBO}	60 -40	Vdc		
Emitter – Base Voltage (NPN) (PNP)	V _{EBO}	6.0 -5.0	Vdc		
Collector Current – Continuous (NPN) (PNP)	Ι _C	200 200	mAdc		
Electrostatic Discharge	ESD	HBM>16000, MM>2000	V		

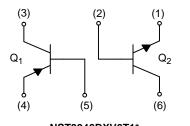
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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NST3946DXV6T1*

*Q1 PNP Q2 NPN

MARKING DIAGRAM



46 = Specific Device Code

- M = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NST3946DXV6T1G	SOT–563 (Pb-Free)	4,000 / Tape & Reel
NSVT3946DXV6T1G	SOT-563 (Pb-Free)	4,000 / Tape & Reel
NST3946DXV6T5G	SOT-563 (Pb-Free)	8,000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Table 2. THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)		Symbol	Max	Unit
Total Device Dissipation Derate above 25°C	T _A = 25°C	PD	357 (Note 1) 2.9	mW mW/°C
			(Note 1)	
Thermal Resistance Junction-to-Ambient		$R_{ hetaJA}$	350 (Note 1)	°C/W
Characteristic (Both Junctions Heated)		Symbol	Max	Unit
Total Device Dissipation	$T_A = 25^{\circ}C$	PD	500 (Note 1)	mW
Derate above 25°C			4.0 (Note 1)	mW/°C
Thermal Resistance Junction-to-Ambient		R_{\thetaJA}	250 (Note 1)	°C/W
Junction and Storage Temperature Range		T _J , T _{stq}	55 to +150	°C

1. FR-4 @ Minimum Pad

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

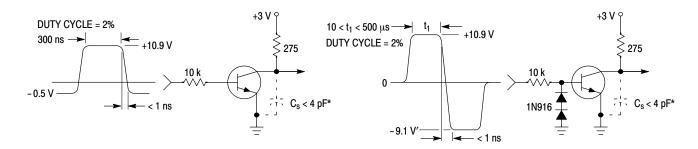
Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (Note 2) ($I_C = 1.0 \text{ mAdc}, I_B = 0$) ($I_C = -1.0 \text{ mAdc}, I_B = 0$)	(NPN) (PNP)	V _{(BR)CEO}	40 40		Vdc
Collector–Base Breakdown Voltage ($I_C = 10 \ \mu Adc, I_E = 0$) ($I_C = -10 \ \mu Adc, I_E = 0$)	(NPN) (PNP)	V _{(BR)CBO}	60 40		Vdc
Emitter – Base Breakdown Voltage ($I_E = 10 \ \mu Adc, I_C = 0$) ($I_E = -10 \ \mu Adc, I_C = 0$)	(NPN) (PNP)	V _{(BR)EBO}	6.0 -5.0		Vdc
Base Cutoff Current ($V_{CE} = 30 \text{ Vdc}, V_{EB} = 3.0 \text{ Vdc}$) ($V_{CE} = -30 \text{ Vdc}, V_{EB} = -3.0 \text{ Vdc}$)	(NPN) (PNP)	I _{BL}		50 50	nAdc
Collector Cutoff Current ($V_{CE} = 30 \text{ Vdc}, V_{EB} = 3.0 \text{ Vdc}$) ($V_{CE} = -30 \text{ Vdc}, V_{EB} = -3.0 \text{ Vdc}$)	(NPN) (PNP)	I _{CEX}		50 50	nAdc
ON CHARACTERISTICS (Note 2)					
$ \begin{array}{l} \text{DC Current Gain} \\ (I_{C} = 0.1 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}) \\ (I_{C} = 1.0 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}) \\ (I_{C} = 10 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}) \\ (I_{C} = 50 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}) \\ (I_{C} = 100 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}) \end{array} $	(NPN)	h _{FE}	40 70 100 60 30	 300 	_
	(PNP)		60 80 100 60 30	_ 300 _	
Collector – Emitter Saturation Voltage ($I_C = 10 \text{ mAdc}, I_B = 1.0 \text{ mAdc}$) ($I_C = 50 \text{ mAdc}, I_B = 5.0 \text{ mAdc}$)	(NPN)	V _{CE(sat)}		0.2 0.3	Vdc
$(I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc})$ $(I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc})$	(PNP)			-0.25 -0.4	
Base – Emitter Saturation Voltage ($I_C = 10 \text{ mAdc}, I_B = 1.0 \text{ mAdc}$) ($I_C = 50 \text{ mAdc}, I_B = 5.0 \text{ mAdc}$)	(NPN)	V _{BE(sat)}	0.65 -	0.85 0.95	Vdc
$(I_{C} = -10 \text{ mAdc}, I_{B} = -1.0 \text{ mAdc})$ $(I_{C} = -50 \text{ mAdc}, I_{B} = -5.0 \text{ mAdc})$	(PNP)		-0.65 -	-0.85 -0.95	

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted) (continued)

Characteristic		Symbol	Min	Max	Unit
SMALL-SIGNAL CHARACTERISTICS			•	•	
$ Current-Gain - Bandwidth Product \\ (I_C = 10 mAdc, V_{CE} = 20 Vdc, f = 100 MHz) \\ (I_C = -10 mAdc, V_{CE} = -20 Vdc, f = 100 MHz) $	(NPN) (PNP)	f _T	300 250		MHz
Output Capacitance ($V_{CB} = 5.0 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz}$) ($V_{CB} = -5.0 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz}$)	(NPN) (PNP)	C _{obo}		4.0 4.5	pF
Input Capacitance ($V_{EB} = 0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz}$) ($V_{EB} = -0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz}$)	(NPN) (PNP)	C _{ibo}		8.0 10.0	pF
Input Impedance ($V_{CE} = 10 \text{ Vdc}, I_C = 1.0 \text{ mAdc}, f = 1.0 \text{ kHz}$) ($V_{CE} = -10 \text{ Vdc}, I_C = -1.0 \text{ mAdc}, f = 1.0 \text{ kHz}$)	(NPN) (PNP)	h _{ie}	1.0 2.0	10 12	kΩ
Voltage Feedback Ratio ($V_{CE} = 10 \text{ Vdc}, I_C = 1.0 \text{ mAdc}, f = 1.0 \text{ kHz}$) ($V_{CE} = -10 \text{ Vdc}, I_C = -1.0 \text{ mAdc}, f = 1.0 \text{ kHz}$)	(NPN) (PNP)	h _{re}	0.5 0.1	8.0 10	X 10 ⁻⁴
$ Small - Signal Current Gain \\ (V_{CE} = 10 Vdc, I_{C} = 1.0 mAdc, f = 1.0 kHz) \\ (V_{CE} = -10 Vdc, I_{C} = -1.0 mAdc, f = 1.0 kHz) $	(NPN) (PNP)	h _{fe}	100 100	400 400	-
Output Admittance ($V_{CE} = 10 \text{ Vdc}, I_C = 1.0 \text{ mAdc}, f = 1.0 \text{ kHz}$) ($V_{CE} = -10 \text{ Vdc}, I_C = -1.0 \text{ mAdc}, f = 1.0 \text{ kHz}$)	(NPN) (PNP)	h _{oe}	1.0 3.0	40 60	μmhos
Noise Figure ($V_{CE} = 5.0 \text{ Vdc}, I_C = 100 \mu \text{Adc}, R_S = 1.0 \text{ k} \Omega, f = 1.0 \text{ kHz}$) ($V_{CE} = -5.0 \text{ Vdc}, I_C = -100 \mu \text{Adc}, R_S = 1.0 \text{ k} \Omega, f = 1.0 \text{ kHz}$)	(NPN) (PNP)	NF		5.0 4.0	dB
SWITCHING CHARACTERISTICS					
Delay Time (V _{CC} = 3.0 Vdc, V _{BE} = -0.5 Vdc) (V _{CC} = -3.0 Vdc, V _{BE} = 0.5 Vdc)	(NPN) (PNP)	t _d		35 35	ns
Rise Time $(I_{C} = 10 \text{ mAdc}, I_{B1} = 1.0 \text{ mAdc})$ $(I_{C} = -10 \text{ mAdc}, I_{B1} = -1.0 \text{ mAdc})$	(NPN) (PNP)	t _r	-	35 35	
Storage Time $(V_{CC} = 3.0 \text{ Vdc}, I_C = 10 \text{ mAdc})$ $(V_{CC} = -3.0 \text{ Vdc}, I_C = -10 \text{ mAdc})$	(NPN) (PNP)	t _s		200 225	ns
Fall Time $(I_{B1} = I_{B2} = 1.0 \text{ mAdc})$ $(I_{B1} = I_{B2} = -1.0 \text{ mAdc})$	(NPN) (PNP)	t _f		50 75	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: Pulse Width \leq 300 µs; Duty Cycle \leq 2.0%.

(NPN)



* Total shunt capacitance of test jig and connectors

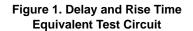
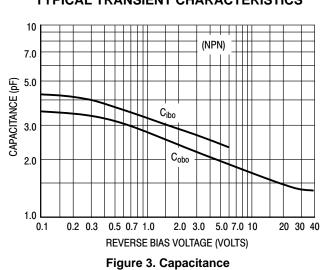
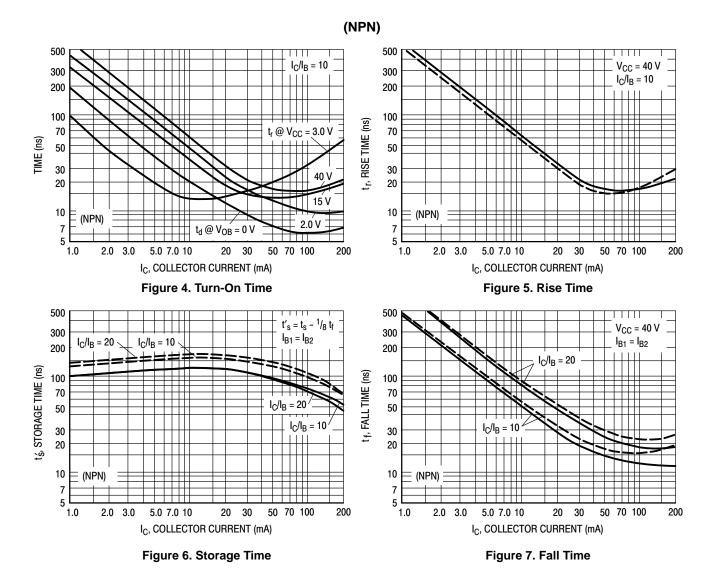


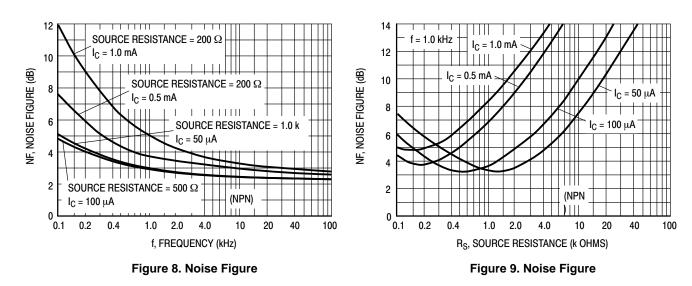
Figure 2. Storage and Fall Time Equivalent Test Circuit



TYPICAL TRANSIENT CHARACTERISTICS



TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

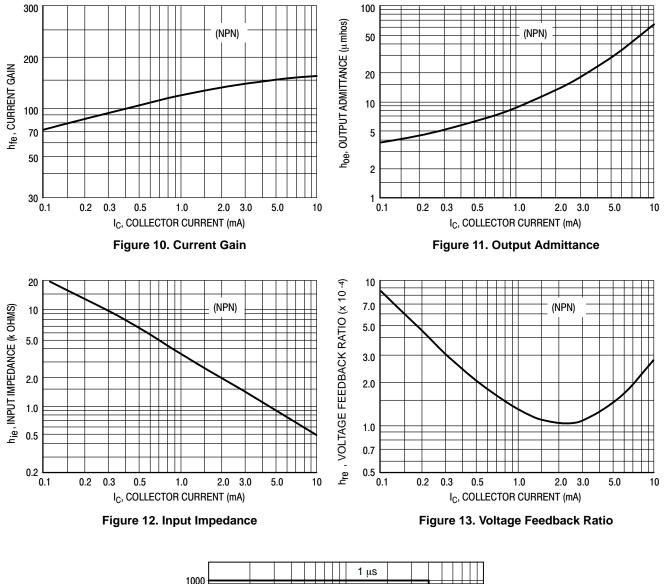


 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C}, \text{ Bandwidth} = 1.0 \text{ Hz})$

(NPN)

h PARAMETERS

(V_{CE} = 10 Vdc, f = 1.0 kHz, T_A = 25°C)



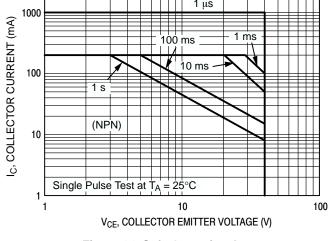
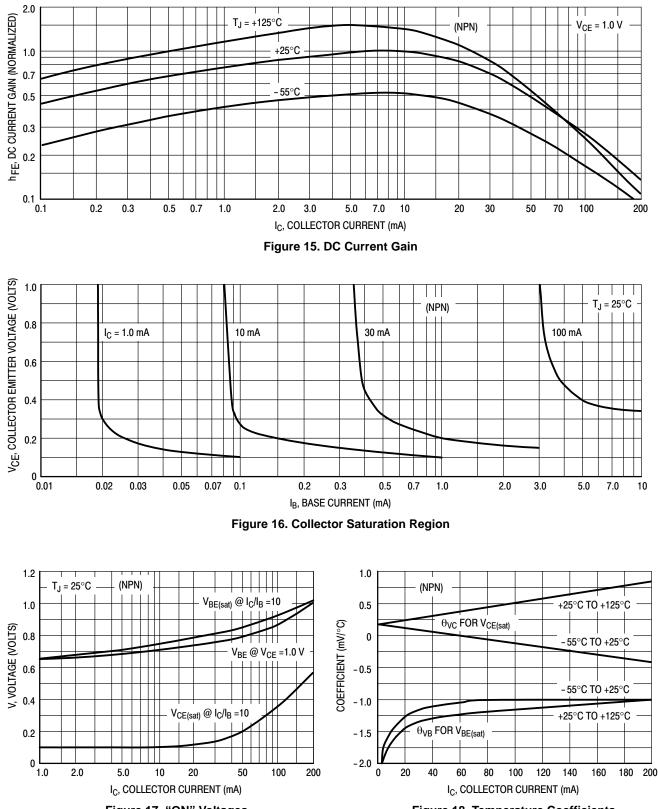


Figure 14. Safe Operating Area

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(NPN)

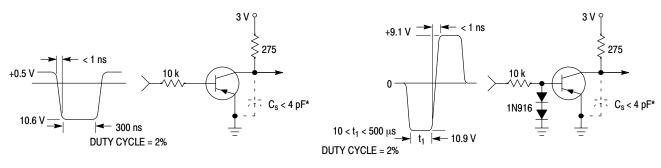








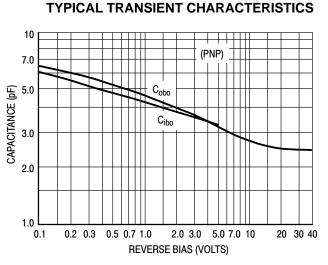
(PNP)



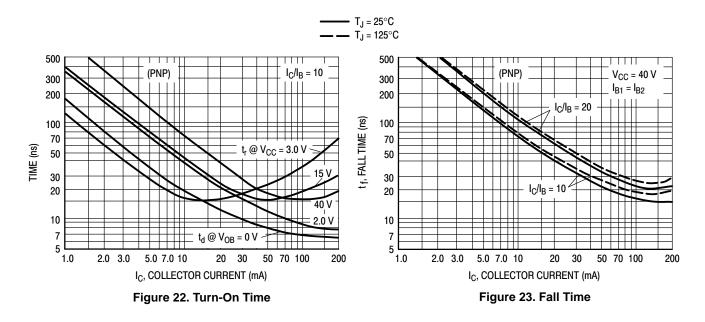
* Total shunt capacitance of test jig and connectors

Figure 19. Delay and Rise Time Equivalent Test Circuit

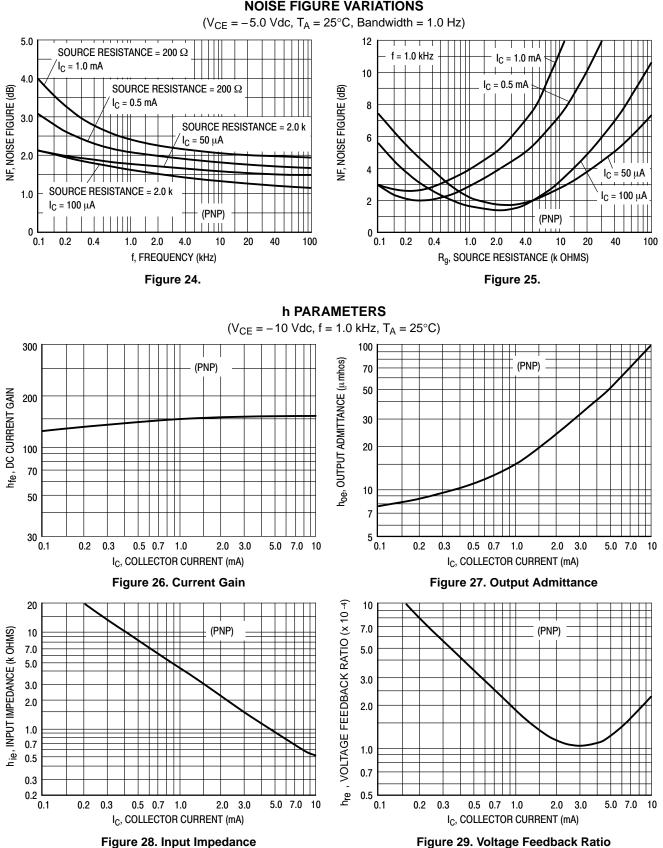
Figure 20. Storage and Fall Time Equivalent Test Circuit







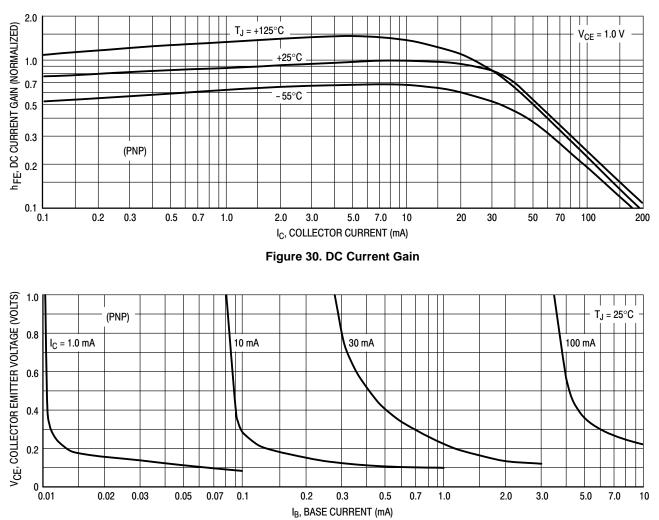
(PNP)



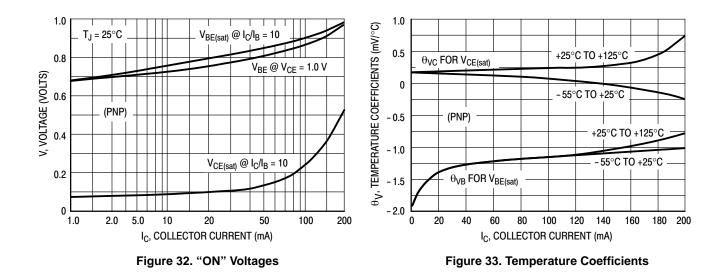
TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

(PNP)









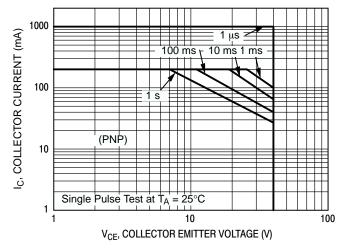


Figure 34. Safe Operating Area

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MILLIMETERS

NDM.

0.55

0.22

0.13

1.60

1.20

0.50 BSC

0.20

1.60

MAX.

0.60

0.27

0.18

1.70

1.30

0.30

1.70

SIDE VIEW

MIN.

0.50

0.17

0.08

1.50

1.10

0.10

1.50

DIM

Α

b

С

D E

e L

 H_E



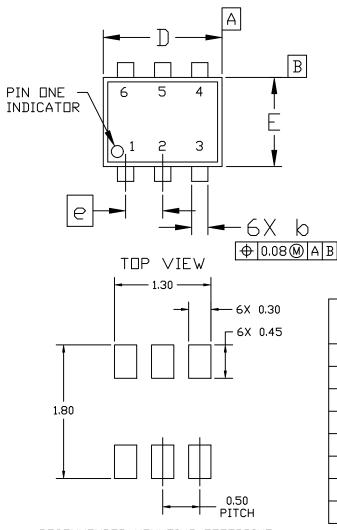


SOT-563, 6 LEAD CASE 463A ISSUE H

DATE 26 JAN 2021

ALE 4:1

- NDTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 1. DIMENSIONING AND TOLERANCING PER A 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS DF BASE MATERIAL.



RECOMMENDED MOUNTING FOOTPRINT* * For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

	SOT-563, 6 LEAD		PAGE 1 OF 2
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STYLE 1:	STYLE 2:	STYLE 3:
PIN 1. EMITTER 1	PIN 1. EMITTER 1	PIN 1. CATHIDE 1
2. BASE 1	2. EMITTER 2	2. CATHIDE 1
3. COLLECTOR 2	3. BASE 2	3. ANUDE/ANUDE 2
4. EMITTER 2	4. COLLECTOR 2	4. CATHIDE 2
5. BASE 2	5. BASE 1	5. CATHIDE 2
6. COLLECTOR 1	6. COLLECTOR 1	6. ANUDE/ANUDE 1
STYLE 4:	STYLE 5:	STYLE 6:
PIN 1. COLLECTOR	PIN 1. CATHEDE	PIN 1. CATHODE
2. COLLECTOR	2. CATHEDE	2. ANODE
3. BASE	3. ANEDE	3. CATHODE
4. EMITTER	4. ANEDE	4. CATHODE
5. COLLECTOR	5. CATHEDE	5. CATHODE
6. COLLECTOR	6. CATHEDE	6. CATHODE
STYLE 7:	STYLE 8:	STYLE 9:
PIN 1. CATHODE	PIN 1. DRAIN	PIN 1. SDURCE 1
2. ANODE	2. DRAIN	2. GATE 1
3. CATHODE	3. GATE	3. DRAIN 2
4. CATHODE	4. SDURCE	4. SDURCE 2
5. ANODE	5. DRAIN	5. GATE 2
6. CATHODE	6. DRAIN	6. DRAIN 1
STYLE 10: PIN 1. CATHIDE 1 2. N/C 3. CATHIDE 2 4. ANIDE 2 5. N/C 6. ANIDE 1	STYLE 11: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	

6. COLLECTOR 2

DATE 26 JAN 2021

GENERIC **MARKING DIAGRAM***



XX = Specific Device Code

M = Month Code

. = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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